



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-05-03
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L9997ND013TR	J5Z7*U726BAZ	A	MU1A	2013-05-03
Amount		UoM	Unit type	ST ECOPACK Grade
532.29		mg	Each	ECOPACK® 1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	ium/Gold (Ni/Pd/Au) Tin/Bismuth (S	Alloy 42		

Package Designator	Size	Nbr of instances	Shape	
CHP	12.8X7.5X2.3	20	flat	
Comment				

Material Composition Declaration						Mfr Item Name	JSZ7*U726BAZ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	5.979	mg	supplier	die	Silicon (Si)	7440-21-3		5.815	mg	972571	10924
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.033	mg	5519	62
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.033	mg	5519	62
die (s)				supplier	metallization	Tantalum (Ta)	7440-25-7		0.001	mg	167	2
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.019	mg	3178	36
die (s)				supplier	passivation	Indium Tin oxide (In2O3.SnO2)	50926-11-9		0.078	mg	13046	147
Leadframe	Copper & its alloys	174.29	mg	supplier	alloy	Copper (Cu)	7440-50-8		168.918	mg	969178	317342
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		3.973	mg	22795	7464
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.239	mg	1371	449
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.208	mg	1193	391
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.873	mg	5009	1640
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.056	mg	321	105
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.023	mg	132	43
Die attach		1.395	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		1.074	mg	769892	2018
Die attach				supplier	glue or tape	Epoxy Cresol Novolak	29690-82-2		0.318	mg	227957	597
Die attach				JIG Table B	glue or tape	Dibutyl Phthalate	84-74-2		0.003	mg	2151	6
Bonding wire		0.705		supplier	wire	Gold (Au)	7440-57-5		0.705	mg	1000000	1324
encapsulation		349.92	mg	supplier	mold compound	Silica, vitreous	60676-86-0		279.937	mg	800003	525911
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		24.494	mg	69999	46016
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		13.997	mg	40001	26296
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		20.995	mg	59999	39443
encapsulation				JIG Table B	mold compound	Antimony Trioxide	1309-64-4		4.199	mg	12000	7889
encapsulation				JIG Table B	mold compound	Brominated Epoxy Resin	40039-93-8		5.248	mg	14998	9859
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		1.05	mg	3001	1973